



Final Product Change Notification

202101021F01 : Assembly Site Transfer from UDG to ASECL for MK22FN512VFX12
10x10QFN88

Note: This notice is NXP Company Proprietary.

Issue Date: Feb 08, 2021 **Effective date:** May 09, 2021

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Change Category

<input type="checkbox"/> Wafer Fab Process	<input type="checkbox"/> Assembly Process	<input type="checkbox"/> Product Marking	<input type="checkbox"/> Test Process	<input type="checkbox"/> Design
<input type="checkbox"/> Wafer Fab Materials	<input checked="" type="checkbox"/> Assembly Materials	<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Equipment	<input type="checkbox"/> Errata
<input type="checkbox"/> Wafer Fab Location	<input checked="" type="checkbox"/> Assembly Location	<input type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Location	<input type="checkbox"/> Electrical spec./Test coverage
<input type="checkbox"/> Firmware	<input type="checkbox"/> Other			

PCN Overview

Description

NXP Semiconductor is announcing the assembly site transfer for MK22FN512VFX12 10x10QFN88 from United Test and Assembly Center Ltd, Dongguan, China(UDG) Assembly Facility to ASE-CL, CHUNG-LI, TAIWAN (ASECHUNG) Assembly Facility.

The change in assembly site also include change in Epoxy and mold compound.

Reason

NXP will close business with UDG soon.

Identification of Affected Products

There is no change to orderable part number.

Change in package trace code is explained under the 'Remarks' section below.

Product Availability

Sample Information

Samples are available upon request

Samples with part number PK22FN512VFX12 will be provided upon request.

Production

Planned first shipment Jul 01, 2021

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No Impact on form, fit, function, reliability or quality

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

Existing inventory will be shipped until depleted

Timing and Logistics

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by Mar 10, 2021.

Remarks

The assembly site is reflected in the package trace code.

The format for the NXP standard trace code:

AWLYYWWZ

A=Assembly Location, WL=Wafer Lot, YYWW=Date Code, Z =Assembly Lot Split,

The marking for UDG is A=CR.

The marking for ASECL is A=X.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

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NXP Quality Management Team.

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Affected Part Numbers

MK22FN512VFX12R

MK22FN512VFX12